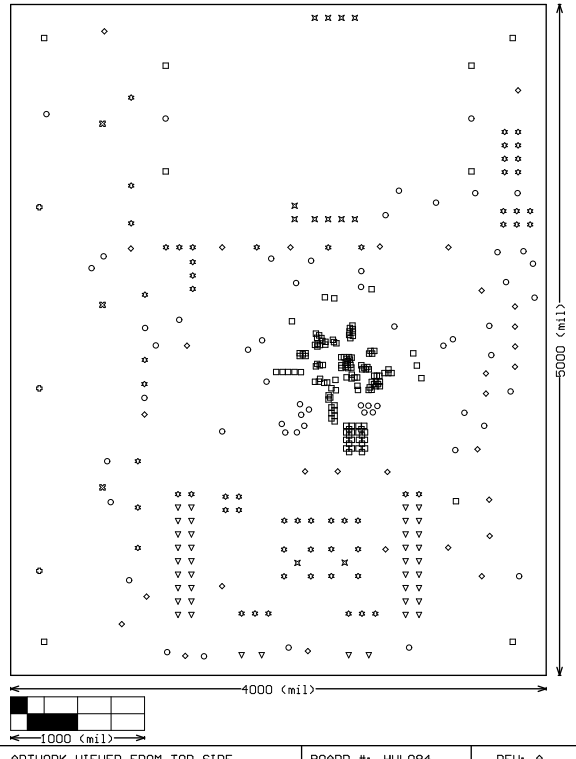
Symbol	Hit Count	Tool Size	Plated	Hole Type
□	135	8mil (0.203mm)	PTH	Round
○	55	28mil (0.711mm)	PTH	Round
⌑	10	39.37mil (1mm)	PTH	Round
✡	52	40mil (1.016mm)	PTH	Round
▽	36	40.157mil (1.02mm)	PTH	Round
▽	4	43.307mil (1.1mm)	PTH	Round
✪	3	45mil (1.143mm)	NPTH	Round
⌑	2	46mil (1.168mm)	PTH	Round
◇	30	63mil (1.6mm)	PTH	Round
⊠	3	65mil (1.651mm)	NPTH	Round
✡	8	67mil (1.702mm)	PTH	Round
○	2	86.614mil (2.2mm)	PTH	Round
□	8	125.984mil (3.2mm)	PTH	Round
	348 Total			

Drill Table



Layer Stack Up Detail for: HVL084A.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
			FR-4
VDD/VDDINTF#3	(.G1)	1.4mil	
			FR-4
GND/GNDP#4	(.G2)	1.4mil	
			FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
4000MIL X 5000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 6 MIL
MIN. CLEARANCE: 3 MIL
MIN. VIA PAD SIZE: 16 MIL
MINIMUM ANNULAR RING 0.101mm (4MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[ ] GREEN [ ] BLUE [X] OTHER RED
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TCA5013EVM
DESIGNED FOR: Public Release
FILE NAME: HVL084A.PcbDoc

ENGINEER: Brian Berner	LAYOUT BY: Brian Berner
SCALE: 0.70	ALTIUM DESIGNER VERSION: 10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 5/16/2014 1:14:02 PM		TEXAS INSTRUMENTS

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